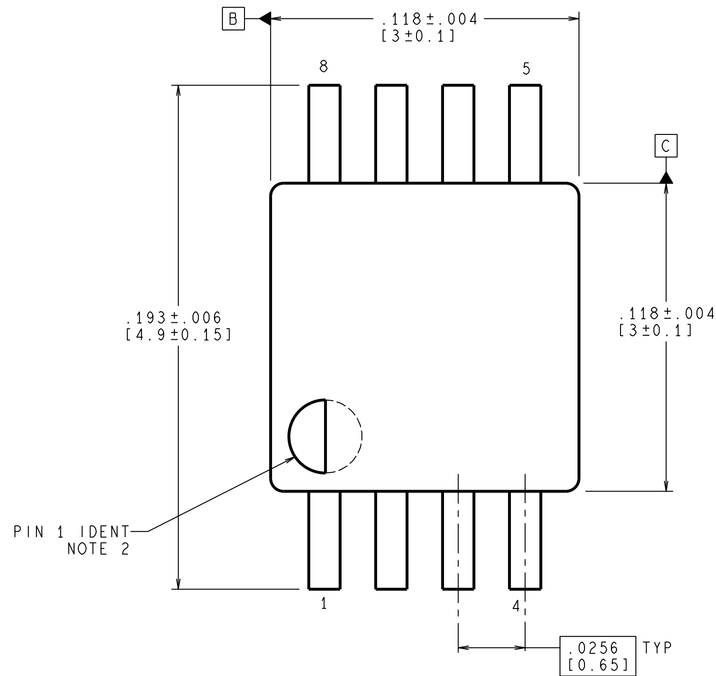
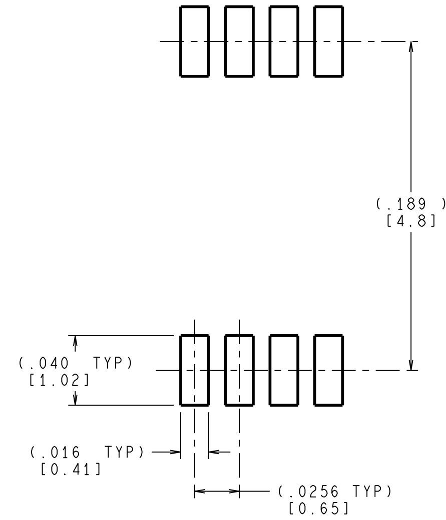
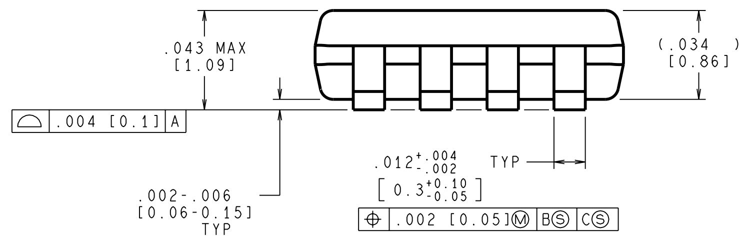
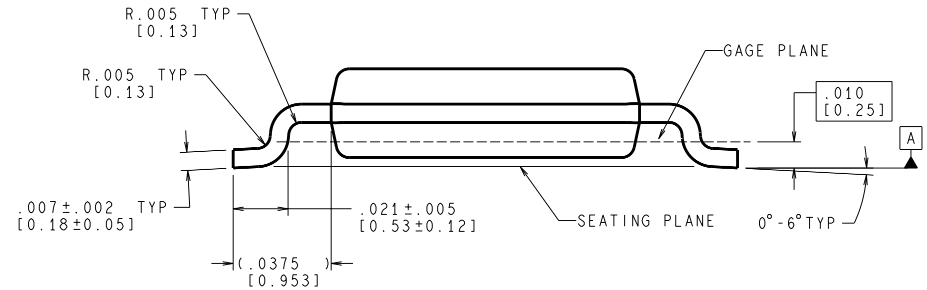
REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	11620	11/18/1996	TL/FL
B	DIM .043 MAX WAS .030-.037; DIM (.034) WAS (.033); DIM .193±.006 WAS .193±.004	11634	01/07/1997	MS/FL
C	COPLANARITY .004[0.1] WAS .002[0.05]; NOTE 1: 200 WAS 150, 5.08 WAS 3.81	11932	02/24/1998	MS/CD
D	DIM .043 MAX WAS .034	12170	03/12/1999	MS/





LAND PATTERN RECOMMENDATION





CONTROLLING DIMENSION IS INCH
VALUES IN [ ] ARE MILLIMETERS

NOTES: UNLESS OTHERWISE SPECIFIED

1. STANDARD LEAD FINISH TO BE 200 MICROINCHES/ 5.08 MICROMETERS MINIMUM TIN/LEAD (SOLDER) ON COPPER.
2. PIN 1 IDENTIFICATION TO HAVE HALF OR FULL CIRCLE OPTION.
3. REFERENCE JEDEC REGISTRATION MO-187, VARIATION AA, DATED MAR 1996.

APPROVALS	DATE
DRAWN T. LEQUANG	11/18/1996
DFTG. CHK.	
ENGR. CHK.	

National Semiconductor
2900 Semiconductor dr, Santa Clara, CA 95052-8090

MOLDED PACKAGE, MINI-SO, .118 WIDE, 8 LEAD

PROJECTION	SCALE	SIZE	DRAWING NUMBER	REV
INCH [MM]	N/A	C	(SC)MKT-MUA08A	D

DO NOT SCALE DRAWING — SHEET 1 of 1